

PROCESS FOR MAKING CIRCUIT BOARD OR LEAD FRAME

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ABSTRACT OF THE DISCLOSURE

10 A process for making a circuit board comprises the following steps of: half-etching a metal layer formed on an insulating substrate by means of a first masking which is positioned on an upper surface of the metal layer; applying a positive liquid resist on the half-etched metal layer from an upper side of the first masking; exposing the positive liquid resist with parallel light
15 from the upper side of the first masking and developing the positive liquid resist in such a manner that a part of the positive liquid resist located under the first masking is protected to be unexposed and undeveloped; etching again the metal layer by means of a second
20 masking composed of the first masking and the protected positive liquid resist to form a conductive pattern on the insulating substrate; and removing the first masking and the second masking from the metal layer.